

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	9	("5796163" "6201305" "6586676" "6624504").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 12:02
S2	6859	@ad<="20031230" and (257/668).ccls. or (257/737-738).ccls. or (257/780-781).ccls. or (257/E21.503).ccls. or (257/E23.119).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:34
S3	5226	@ad<="20031230" and (257/734).ccls. or (257/784).ccls. or (257/779).ccls. or (257/786).ccls. or (257/792).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 12:17
S4	1	@ad<="20031230" and (257/668).ccls. and 'solder contact' same 'pad' same 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 14:24
S5	1	@ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 13:37
S6	44	@ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 13:41
S7	3	@ad<="20031230" and (257/668).ccls. and 'bonding pad' same 'compliant layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:57
S8	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:45
S9	1	"6043563".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:47
S10	1	"5885849".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:48
S11	1	"4736236".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:52
S12	1	"4670770".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:52
S13	1	"4612566".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:53
S14	1	"4527330".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:53
S15	1	"4413308".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:53

S16	1	"4232512".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:54
S17	1	"4215359".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:56
S18	1	"4200975".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:56
S19	4	@ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:05
S20	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:58
S21	1	"6043563".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:58
S22	1	"5929517".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:58
S23	1	"5885849".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:59
S24	1	"5749997".PN.	USPAT; USOCR	OR	ON	2005/02/03 13:59
S25	1	"5679977".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:00
S26	1	"5666270".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:01
S27	1	"5180311".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:02
S28	1	@ad<="20031230" and (257/668). ccls. and 'bonding pad' same 'Resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:08
S29	3	@ad<="20031230" and (257/668). ccls. and 'pad' same 'compliance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:09
S30	111	@ad<="20031230" and 'bonding pad' same 'Resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:09
S31	12	@ad<="20031230" and 'bonding pad' same 'Resilience'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:09
S33	30	@ad<="20031230" and (257/668). ccls. and 'pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:04

S34	44	@ad<="20031230" and 'bonding pad' same 'compliance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:10
S35	136	@ad<="20031230" and 'bonding pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:10
S36	3	@ad<="20031230" and 'solder contact' same 'pad' same 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:11
S37	919	@ad<="20031230" and 'pad' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:44
S38	11	@ad<="20031230" and 'solder' and 'pad' with 'different' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:13
S39	3685	@ad<="20031230" and (257/668).ccls. or (257/737-738).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:34
S40	1	"6049130".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:35
S41	1	"6034431".PN.	USPAT; USOCR	OR	ON	2005/02/03 14:36
S42	570	@ad<="20031230" and 'compliant contact'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:05
S43	74	@ad<="20031230" and 'solder ball' and 'compliant contact'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:05
S44	1	"6333563".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:18
S45	1	"6221697".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:19
S46	1	"6443351".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:22
S47	1	"6409073".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:23
S48	1	"6396156".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:23

S49	1	"6369451".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:24
S50	1	"6333104".PN.	USPAT; USOCR	OR	ON	2005/02/03 15:24
S51	20	@ad<="20031230" and 'bonding pad' with 'modulus'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:44
S53	219	@ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:45
S54	81	@ad<="20031230" and 'bonding pad' and 'solder ball' and 'compliant layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 15:45
S55	11	((("6333559") or ("6376279") or ("6541844") or ("6465867") or ("6204165")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 08:49
S56	2	("6211572").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 08:49
S57	1	"5874782".PN.	USPAT; USOCR	OR	ON	2005/02/04 08:50
S58	1	"5777379".PN.	USPAT; USOCR	OR	ON	2005/02/04 08:52
S59	1	"5679977".PN.	USPAT; USOCR	OR	ON	2005/02/04 08:57
S61	233	@ad<="20031230" and 'compliant' with 'packaging'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:58
S62	92	@ad<="20031230" and 'bonding pad' and 'compliant' with 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:59
S63	2	@ad<="20031230" and 'bonding pad' same 'compliant' with 'packaging'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 08:59
S64	1	"5001302".PN.	USPAT; USOCR	OR	ON	2005/06/17 14:23

S69	1	"5777379".PN.	USPAT; USOCR	OR	ON	2005/06/17 14:36
S70	1	"5677576".PN.	USPAT; USOCR	OR	ON	2005/06/17 14:36
S73	1	"6333565".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:18
S74	1	"6277669".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:21
S75	117	@ad<="20031230" and 'solder ball' same 'contact pad' same 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:04
S76	570	@ad<="20031230" and 'solder ball' and 'contact pad' and 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:23
S77	607	@ad<="20031230" and 'contact pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:23
S78	1289	@ad<="20031230" and 'contact pad' same 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:23
S79	13	@ad<="20031230" and 'solder ball' with 'contact pad' same 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:43
S80	18	@ad<="20031230" and 'solder ball' with 'contact pad' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:45
S81	1543	@ad<="20031230" and 'pad' same 'contact' same 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:24
S82	8	@ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:25
S83	77	@ad<="20031230" and 'solder ball' and 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:25
S84	1	"5956235".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:32

S85	1	"5868304".PN.	USPAT; USOCR	OR	ON	2005/06/17 15:32
S86	81	@ad<="20031230" and 'solder ball' and 'contact pad' with 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:43
S87	8	@ad<="20031230" and 'solder ball' same 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 15:45
S89	739	@ad<="20031230" and 'contact pad' with 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:05
S90	302	@ad<="20031230" and 'contact pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S91	57	@ad<="20031230" and 'bonding pad' with 'compliant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S92	58	@ad<="20031230" and 'bonding pad' with 'resilient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S93	576	@ad<="20031230" and 'bonding pad' with 'flexible'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/17 16:12
S94	1	"6147401".PN.	USPAT; USOCR	OR	ON	2005/06/17 16:14
S95	1	"6043563".PN.	USPAT; USOCR	OR	ON	2005/06/17 16:14